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COOLING MECHANISM FOR ELECTRONIC DEVICE

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PURPOSE: To maximize contact area and improve cooling efficiency by mounting a cooling part to the inside of a cover at the cooling part using only spring means and by pressing the cooling part to an electronic device by revolution of a cam for contacting.

CONSTITUTION: An electronic device 51 to be cooled is set to a cooling frame 2 and is moved to the front of a cooling part 1. The cooling part 1 is pushed toward an electronic device 51 for adhesion. At this time, when the cooling part of the electronic device 51 is slanted, the cooling part 1 is slanted by deformation of a spring means which is provided between a cooling plate cover 3 and the cooling part 1 and is pressed toward the electronic device 51, thus enabling the cooling part 1 to contact with the entire surface of the cooling part of the electronic device 51. Water is allowed to flow to a water pipe for cooling 50 which is incorporated in the cooling part, thus cooling the electronic device 51. When cooling is completed, the cam 53 is allowed to rotate again, thus stopping pressing of the cooling part against the electronic device. The electronic device is taken out of the cooling frame and cooling is completed.

